

L Number	Hits	Search Text	DB	Time stamp
-	690	(216/24).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 12:18
-	135	(216/26).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 09:27
-	83	(216/31).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 09:28
-	126	(216/55).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 09:29
-	170	(216/85).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 11:56
-	307	(216/87).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 09:29
-	106	(216/94).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 09:30
-	552	(216/97).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/12 16:26
-	2	("5057184").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 09:31
-	463	(216/65).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 09:33
-	386	(etch\$3 and (heat\$3 or radiation) and (computer or controller)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 09:41
-	129	(etch\$3 and (heat\$3 or radiation) and (computer or controller) and (etchant or solution or liquid or wet or wet\$1etch\$3)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 15:24
-	263	((216/24).CCLS.) or ((216/26).CCLS.) or ((216/31).CCLS.) or ((216/55).CCLS.) or ((216/85).CCLS.) or ((216/87).CCLS.) or ((216/94).CCLS.) or ((216/97).CCLS.)) and (computer or controller)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 09:51
-	117	((216/24).CCLS.) or ((216/26).CCLS.) or ((216/31).CCLS.) or ((216/55).CCLS.) or ((216/85).CCLS.) or ((216/87).CCLS.) or ((216/94).CCLS.) or ((216/97).CCLS.)) and (heat\$3 with (local\$2 or specific or selected))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 10:02

-	26	("3833383"   "4049944"   "4289381"   "4340617"   "4489102"   "4512638"   "4514479"   "4523807"   "4664940"   "4746934"   "4778744"   "4818661"   "4843031"   "4857425"   "4859496"   "4859548"   "5250329"   "5543251"   "5745221"   "5748368"   "5771098"   "5796004"   "5810945"   "RE36113"   "5955221"   "5991075").PN.	USPAT	2004/05/04 09:54
-	102	((etchant or (etch\$3 adj solution)) and (heat\$3 with (local\$2 or specific or selected))).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/12 15:50
-	696	((216/55).CCLS.) or ((216/85).CCLS.) or ((216/87).CCLS.) or ((216/94).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/12 16:26
-	171	laser-induced with etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/11 15:21
-	32	(apparatus and etch\$3 and heater\$1 and rate).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 10:33
-	194	(apparatus and etch\$3 and heater\$1).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/12 13:31
-	186	(156/345.1).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 10:35
-	150	(156/345.11).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 10:40
-	70	(156/345.22).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 11:00
-	248	(156/345.24).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 10:37
-	106	(156/345.27).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 11:49
-	143	(156/345.28).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 10:37
-	91	(156/345.15).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 11:39

-	215	((156/345.11).CCLS.) or ((156/345.22).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 10:58
-	2	("6675817").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 10:58
-	38	(apparatus and etch\$3 and heater\$1 and (computer or controller)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 12:12
-	16	(apparatus and etch\$3 and heater\$1 and solution).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 11:22
-	30	radiation-induced with etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 11:25
-	29	etch\$3 same apparatus same heater\$1 same tank	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 15:05
-	173	etch\$3 same heater\$1 same tank	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 11:28
-	4	("2143796"   "3023139"   "3284181"   "5246540").PN.	USPAT	2004/05/04 14:41
-	95	(glass and etch\$3 and heater\$1).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 14:42
-	1495	(glass and etch\$3 and heat\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 14:42
-	431	(etch\$3 and apparatus and (liquid or solution or wet\$8)).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 14:51
-	52	(etch\$3 and apparatus and (liquid or solution or wet\$8)).ti. and heat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 14:47
-	136	(wet and etching and apparatus).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 14:56
-	13	((wet with etch\$3) and (local\$4 with heat\$3)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/04 15:14
-	19	((liquid or solution or wet\$8) and etch\$3 and heater\$1 and (computer or controller)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:31

-	173	etch\$3 same heater\$1 same tank	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 15:06
-	7	((liquid with etch\$3) and (local\$4 with heat\$3)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 15:14
-	21	((solution with etch\$3) and (local\$4 with heat\$3)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 15:19
-	335	((polish\$3 or etch\$3) and (local\$4 with heat\$3)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 16:09
-	911	((polish\$3 or etch\$3) and (select\$3 with heat\$3)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 16:10
-	281	((polish\$3 or etch\$3) and (select\$3 with heat\$3 and (portion or area or region))).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/04 16:11
-	65	((boundary adj layer) and etch\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 11:55
-	505	menisc\$2 same etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 12:02
-	110	menisc\$2 with etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 11:59
-	4	marangoni and rushford.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 12:13
-	4	marangoni and britten.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 12:00
-	85	(menisc\$2 and etch\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 12:08
-	2216	(menisc\$2).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 12:09
-	28	(menisc\$2).ti. and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 12:09
-	34	5660642.URPN.	USPAT	2004/05/05 12:11

-	30	marangoni same etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 12:13
-	77	(etch\$3 and heater\$1 and (computer or controller)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 12:19
-	96	(etch\$3 and (heater\$1 or (heat\$3 adj (element\$1 or electrode\$1))) and (computer or controller)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 12:23
-	922	(etch\$3 and (heater\$1 or (heat\$3 adj (element\$1 or electrode\$1)))).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 12:24
-	198	(etch\$3 and (liquid or solution) and (heater\$1 or (heat\$3 adj (element\$1 or electrode\$1)))).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 12:26
-	1467	(etch\$3 same (liquid or solution or wet)) and ((heater\$1 or (heat\$3 adj (element\$1 or electrode\$1)))).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 12:28
-	362	(134/61).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 12:39
-	91	(134/88).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 12:39
-	52	(134/90).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 12:40
-	83	(134/84).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 11:54
-	496	(65/355).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 14:30
-	365	(392/441).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 14:13
-	187	(219/628).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/12 11:33
-	222	(219/656).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/05 14:31



	4	(etch\$3 and (bath or solution or liquid or etchant)) with (heater\$1 or heating) with (computer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 15:29
	28	(etch\$3 and (bath or solution or liquid or etchant)) with (heater\$1 or heating) with (controller)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 15:30
	2	(etch\$3 and (tank or bath or solution or liquid or etchant)) same ((plural or multiple) with heat\$3 with (zones or regions))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 15:37
	135	(etch\$3 and (tank or bath or lens or solution or liquid or wet)) and ((plural or multiple) with heat\$3 with (zones or regions))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 15:42
	9	(etch\$3 with bath) same (heat\$3 with (zones or regions))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 15:43
	34	(etch\$3 with bath) same (computer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 15:48
	4	(etch\$3 with (bath or solution)) same (thermal adj gradient)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 15:51
	1	(wet adj etch\$3) same (thermal adj gradient)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 12:13
	103	(etch\$3) same (thermal adj gradient)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 15:52
	12	(etch\$3) same (thermal adj gradient) same (solution or acid or bath)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 15:52
	5	(etch\$3 and bath) with (heater\$1 or heating) with (computer or controller)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 16:02
	1957	((216/24).CCLS.) or ((216/26).CCLS.) or ((216/31).CCLS.) or ((216/55).CCLS.) or ((216/85).CCLS.) or ((216/87).CCLS.) or ((216/94).CCLS.) or ((216/97).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 11:30
	393	((216/24).CCLS.) or ((216/26).CCLS.) or ((216/31).CCLS.) or ((216/55).CCLS.) or ((216/85).CCLS.) or ((216/87).CCLS.) or ((216/94).CCLS.) or ((216/97).CCLS.)) and (heater or heating) and (solution or bath) ((etch-rate or (etch adj rate)) with increas\$3 with temperature) same (solution or bath)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 11:32
	48		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 11:34

-	26	(156/345.15).ccls. and (heating or heater)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 11:45
-	28	(156/345.22).ccls. and (heating or heater)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 11:46
-	13	(156/345.27).ccls. not plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 11:50
-	1911	(134/1).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 11:54
-	64	(radiation and etch\$3 and (smoothness or glass or lens\$2 or planar\$4) and (bath or solution)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 11:58
-	21	(apparatus and polish\$3 and heater\$1 and (computer or controller)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 12:15
-	3	(polish\$3 or etch\$3) same (thermal adj gradient) same (boundary adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 12:14
-	168	((polish\$3 or etch\$3) and (solution or bath or etchant) and ((heating adj element\$1) or heater\$1)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 12:24
-	22	((polish\$3 or etch\$3) and (solution or bath or etchant) and interferomet\$7).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 12:18
-	1049	(polish\$3 or etch\$3) and (((heating adj element\$1) or heater\$1) near2 (array or plurality)) and (bath or solution or etchant or acid) and (computer or control\$3 or monitor\$3 or microprocessor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 12:35
-	139	(polish\$3 or etch\$3).ab. and (((heating adj element\$1) or heater\$1) near2 (array or plurality)) and (bath or solution or etchant or acid) and (computer or control\$3 or monitor\$3 or microprocessor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 12:31
-	688	((polish\$3 or etch\$3) and (((heating adj element\$1) or heater\$1) near2 (array or plurality)) and (bath or solution or etchant or acid) and (computer or control\$3 or monitor\$3 or microprocessor)) not (inkjet or ink-jet or (ink adj jet) or printhead or print-head or (print adj head))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 12:32
-	441	((polish\$3 or etch\$3) and (((heating adj element\$1) or heater\$1) near2 (array or plurality)) and (bath or solution or etchant or acid) and (computer or control\$3 or monitor\$3 or microprocessor)) not (inkjet or ink-jet or (ink adj jet) or printhead or print-head or (print adj head) or plasma)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 12:33

	7	(polish\$3 or etch\$3) and (bath or solution or etchant or acid) and (((heating adj element\$1) or heater\$1) with (array or plurality) with (independently adj controlled))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 12:38
	67	((heating adj element\$1) or heater\$1) with (array or plurality) with (independently adj controlled))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 12:39
	8	(("4343116") or ("5605600") or ("5795493") or ("4804977")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 15:00
	15	(rushford or britten).in. and (polish\$3 or etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 15:14
	536	((laser or radiation) and (polish\$3 or etch\$3) and glass).ab. and (solution or etchant or acid or solvent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 15:25
	29	((laser or radiation) and (polish\$3 or etch\$3) and glass).ab. and (solution or etchant or acid or solvent) and computer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 15:20
	17	((laser or radiation) and (polish\$3 or etch\$3) and glass).ab. and (solution or etchant or acid or solvent) and ((heating adj element\$1) or heater\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 15:58
	19	((laser-assisted) and etch\$3).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 16:12
	4	("5660642"   "5882433"   "5934299"   "6257255"   "2001/0045223"   "2002/0074023").PN.	USPAT	2004/05/10 16:08
	357	(laser and (wet adj etch\$3)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 16:14
	136	(laser with (wet adj etch\$3)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/10 16:14
	115	(216/97).ccls. and (laser or radiation or beam)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/11 13:37
	5	(216/97).ccls. and (interferometer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/11 13:32
	2246	(glass with polish\$3) and (laser or radiation or beam) and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/11 13:38

	137	((glass with polish\$3) and (laser or radiation or beam) and etch\$3) and interferometer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 13:39
	57	((glass with polish\$3) and (laser or radiation or beam) and etch\$3) and interferometer and computer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 13:39
	457	(laser adj (assisted or induced or controlled)) with etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:32
	113	((laser adj (assisted or induced or controlled)) with etch\$3) and cool\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:22
	58	((laser adj (assisted or induced or controlled)) with etch\$3).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:36
	28	(cooling adj2 etchant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:37
	14	(cooling adj etchant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:39
	42	(temperature adj control) with etch\$3 with (bath or solution or tank)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:42
	21	(etchant or (etching adj solution)) adj2 cooled	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:44
	48	(temperature adj control) with etchant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:45
	768	(134/105).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/12 11:12
	110	((134/105).CCLS.) and (computer or controller)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/12 11:12
	50	((134/105).CCLS.) and (computer or controller) and (glass or polish\$3 or lens\$2 or etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/12 11:12
	898	(219/121.84).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/12 16:07



